

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Canceled).
2. (Previously Presented) A high-frequency coil device, comprising:
a dielectric substrate; and
a coil formed of a conductive layer embedded in a predetermined coil pattern in the surface of said dielectric substrate, portions of the bottom surface and side surface of said coil being covered by said dielectric substrate, and said coil has other portions which have a gap between a bottom surface of the coil and the substrate.
3. (Canceled).
4. (Currently Amended) The high-frequency coil device as claimed in Claim 2, wherein said ~~resin layer~~ dielectric substrate is a polyimide layer or a liquid crystal polymer layer.
5. (Canceled).
6. (Currently Amended) The high-frequency coil device as claimed in claim 4, wherein said plating conductive layer has a multi-layered structure in which a nickel plating layer and a copper plating layer are laminated.

Claims 7-9 (Canceled).

10. (Previously Presented) A high-frequency coil device, comprising:
a dielectric substrate; and
a coil formed of a conductive layer, portions of the bottom surface of said coil formed in contact with said dielectric substrate, and said coil has other portions which have a gap between a bottom surface of the coil and the substrate.
11. (Currently Amended) The high-frequency coil device as claimed in Claim 10, wherein said ~~resin layer~~ dielectric substrate is a polyimide layer or a liquid crystal polymer layer.
12. (Currently Amended) The high-frequency coil device as claimed in claim 11, wherein said plating conductive layer has a multi-layered structure in which a nickel plating layer and a copper plating layer are laminated.